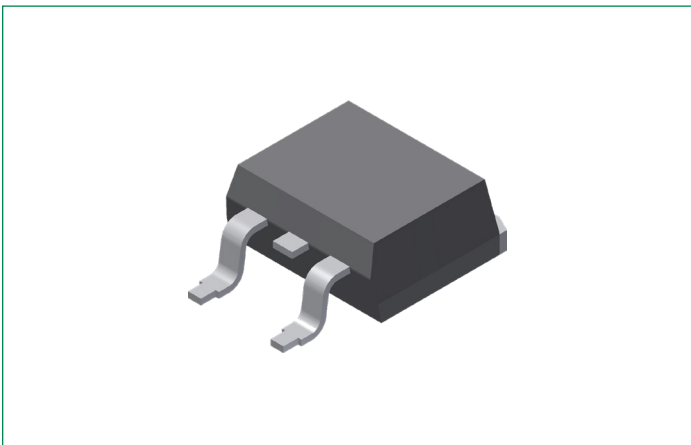


# IXYA60N65A5

650 V, 60 A Gen5 XPT™ IGBT

Extreme Light Punch Through IGBT for up to 5 kHz Switching



## Description:

Developed using our proprietary XPT™ thin-wafer technology and state-of-the-art Trench IGBT process, these devices feature reduced thermal resistance, low conduction losses, and low gate driver requirements.

## Features & Benefits:

- Optimized for Low Conduction Losses
- High Surge Current Capability
- Square RBSOA
- International Standard Package
- Low Gate Charge  $Q_G$
- Low Gate Drive Requirement

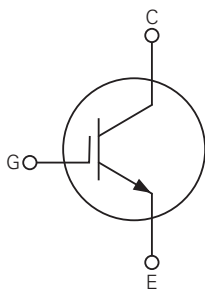
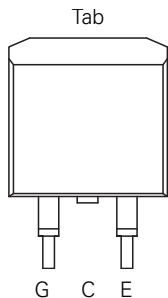
## Applications:

- Power Inverters
- UPS
- PFC Circuits
- Battery Chargers
- Welding Machines
- Lamp Ballasts
- Inrush Current Protection Circuits

## Product Summary

Characteristic	Value	Unit
$V_{CES}$	650	V
$I_{C110}$	60	A
$V_{CE(sat)}$	$\leq 1.35$	V
$t_{fi(typ)}$	110	ns

## Pinout Diagrams TO-263 (IXYA)



**G:** Gate; **C:** Collector; **E:** Emitter; **Tab:** Collector

## Maximum Ratings

Symbol	Characteristic	Conditions	Value	Unit
$V_{CES}$	Collector-Emitter Voltage	$T_J = 25\text{ °C to }175\text{ °C}$	650	V
$V_{CGR}$	Collector-Gate Voltage	$T_J = 25\text{ °C to }175\text{ °C}, R_{GE} = 1\text{ M}\Omega$	650	V
$V_{GES}$	Gate-Emitter Voltage	Continuous	$\pm 20$	V
$V_{GEM}$	Transient Gate-Emitter Voltage	Transient	$\pm 30$	V
$I_{C25}$	Continuous Collector Current	$T_C = 25\text{ °C}$	134	A
$I_{C110}$	Continuous Collector Current	$T_C = 110\text{ °C}$	60	A
$I_{CM}$	Pulsed Collector Current	$T_C = 25\text{ °C}, 1\text{ ms}$	260	A
SSOA (RBSOA)	Switching Safe Operating Area (Reverse Biased Safe Operating Area)	$V_{GE} = 15\text{ V}, T_{VJ} = 150\text{ °C}, R_G = 5\ \Omega,$ Clamped Inductive Load, $I_{CM} = V_{CE} \leq V_{CES}$	108	A
$P_C$	Collector Power Dissipation	$T_C = 25\text{ °C}$	395	W
$T_J$	Junction Temperature	–	–55 to 175	°C
$T_{JM}$	Maximum Junction Temperature	–	175	°C
$T_{stg}$	Storage Temperature	–	–55 to 175	°C
$T_{SOLD}$	Soldering Temperature	TO-263-2L - Plastic Body for 10 s	260	°C
$F_C$	Mounting Force	–	10..65 / 2.2..14.6	N/lb
W	Weight	–	2.5	g

## Thermal Characteristic

Symbol	Characteristic	Value			Unit
		Min.	Typ.	Max.	
$R_{th,JC}$	Thermal Resistance, Junction-to-Case	–	–	0.38	°C/W

## Electrical Characteristics – Static ( $T_J = 25\text{ °C}$ unless otherwise specified)

Symbol	Characteristic	Conditions	Value			Unit
			Min.	Typ.	Max.	
$BV_{CES}$	Collector-Emitter Breakdown Voltage	$I_C = 250\ \mu\text{A}, V_{GE} = 0\text{ V}$	650	–	–	V
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C = 250\ \mu\text{A}, V_{CE} = V_{GE}$	3.7	–	5.8	V
$I_{GES}$	Gate-Emitter Leakage Current	$V_{CE} = 0\text{ V}, V_{GE} = \pm 20\text{ V}$	–	–	$\pm 100$	nA
$I_{CES}$	Zero Gate Voltage Collector Current	$V_{CE} = V_{CES}, V_{GE} = 0\text{ V}$	–	–	10	$\mu\text{A}$
		$V_{CE} = V_{CES}, V_{GE} = 0\text{ V}, T_J = 150\text{ °C}$	–	–	250	$\mu\text{A}$
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage <sup>1</sup>	$I_C = 36\text{ A}, V_{GE} = 15\text{ V}$	–	1.23	1.35	V
		$I_C = 36\text{ A}, V_{GE} = 15\text{ V}, T_J = 150\text{ °C}$	–	1.35	–	V

**Note 1:** Pulse test,  $t \leq 300\ \mu\text{s}$ , duty cycle,  $d \leq 2\%$

## Electrical Characteristics – Dynamic ( $T_J = 25\text{ °C}$ unless otherwise specified)

Symbol	Characteristic	Conditions	Value			Unit	
			Min.	Typ.	Max.		
$g_{fs}$	Transconductance <sup>1</sup>	$I_C = 36\text{ A}, V_{CE} = 10\text{ V}$	20	35	–	S	
$C_{ies}$	Input Capacitance	$V_{GE} = 0\text{ V}, V_{CE} = 25\text{ V}, f = 1\text{ MHz}$	–	1970	–	pF	
$C_{oes}$	Output Capacitance		–	106	–		
$C_{res}$	Reverse Transfer Capacitance		–	80	–		
$Q_{g(on)}$	Total Gate Charge	$V_{GE} = 15\text{ V}, V_{CE} = 0.5 \times V_{CES},$ $I_C = 36\text{ A}$	–	128	–	nC	
$Q_{ge}$	Gate-Emitter Charge		–	13	–		
$Q_{gc}$	Gate-Collector Charge		–	66	–		
$t_{d(on)}$	Turn-on Delay Time <sup>2</sup>	Inductive Load, $V_{GE} = 15\text{ V}, V_{CE} = 400\text{ V},$ $I_C = 36\text{ A}, R_{G(ext)} = 5\ \Omega$	$T_J = 25\text{ °C}$	–	28	–	ns
			$T_J = 150\text{ °C}$	–	19	–	
$t_{ri}$	Turn-on Rise Time <sup>2</sup>		$T_J = 25\text{ °C}$	–	32	–	ns
			$T_J = 150\text{ °C}$	–	32	–	
$E_{on}$	Turn-on Energy <sup>2</sup>		$T_J = 25\text{ °C}$	–	0.60	–	mJ
			$T_J = 150\text{ °C}$	–	1.10	–	
$t_{d(off)}$	Turn-off Delay Time <sup>2</sup>		$T_J = 25\text{ °C}$	–	230	–	ns
			$T_J = 150\text{ °C}$	–	235	–	
$t_{fi}$	Turn-off Fall Time <sup>2</sup>		$T_J = 25\text{ °C}$	–	110	–	ns
			$T_J = 150\text{ °C}$	–	240	–	
$E_{off}$	Turn-off Energy <sup>2</sup>	$T_J = 25\text{ °C}$	–	1.45	–	mJ	
		$T_J = 150\text{ °C}$	–	2.50	–		

**Note 1:** Pulse test,  $t \leq 300\ \mu\text{s}$ , duty cycle,  $d \leq 2\%$

**Note 2:** Switching times and energy losses may increase for higher  $V_{CE(clamp)}$ ,  $T_J$ , or  $R_G$ .

Characteristic Curves

Fig. 1. Output Characteristics @  $T_J = 25^\circ\text{C}$

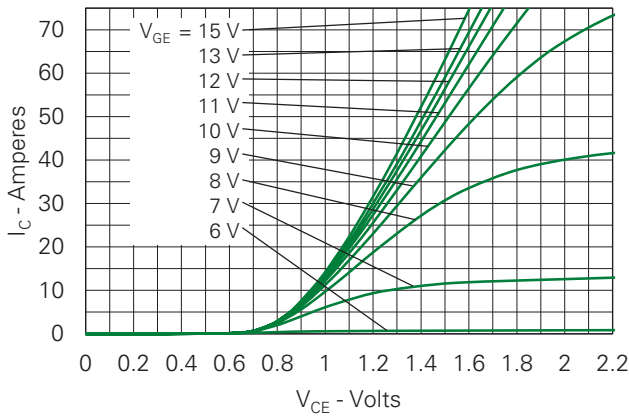


Fig. 2. Extended Output Characteristics @  $T_J = 25^\circ\text{C}$

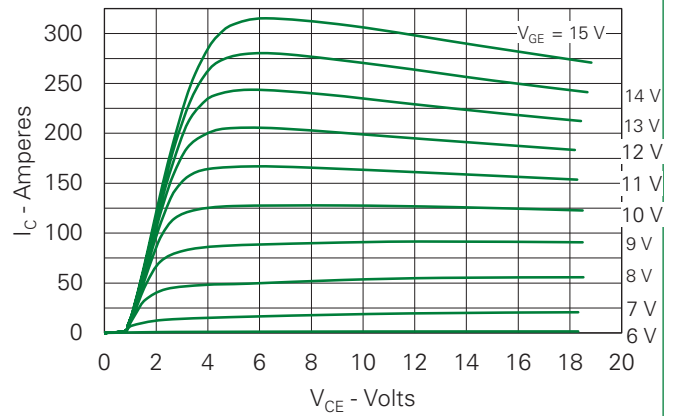


Fig. 3. Output Characteristics @  $T_J = 150^\circ\text{C}$

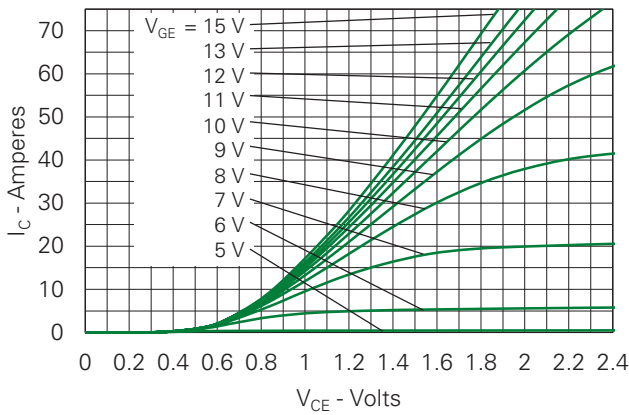


Fig. 4. Dependence of  $V_{CE(sat)}$  on Junction Temperature

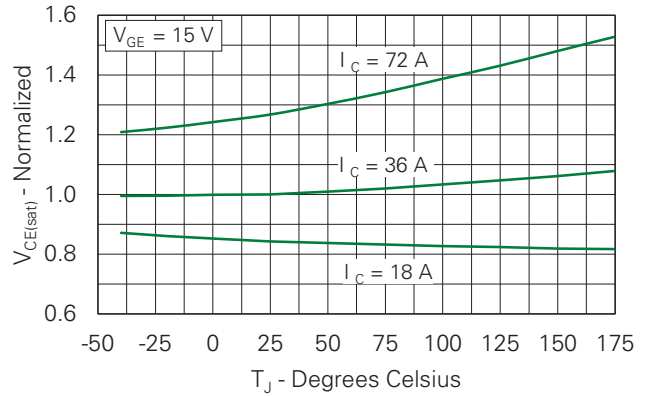


Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage

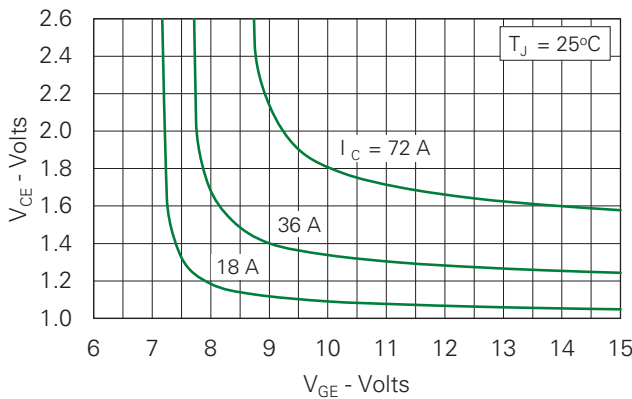


Fig. 6. Input Admittance

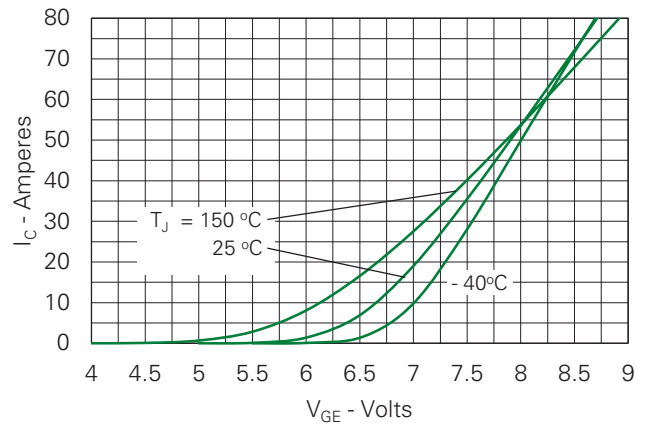


Fig. 7. Transconductance

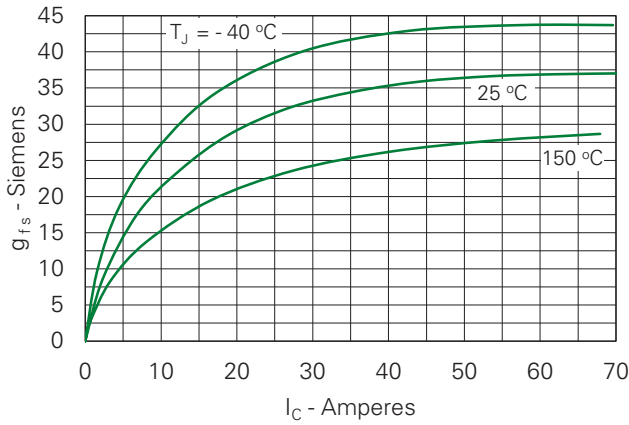


Fig. 8. Gate Charge

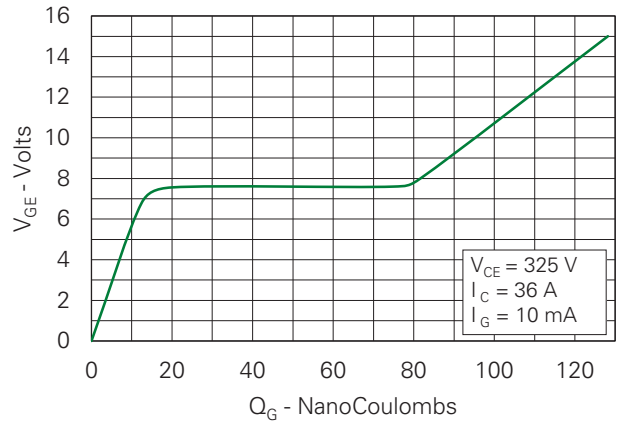


Fig. 9. Capacitance

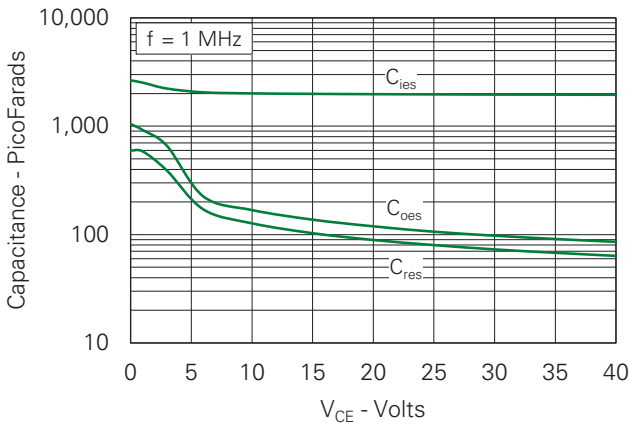


Fig. 10. Reverse-Bias Safe Operating Area

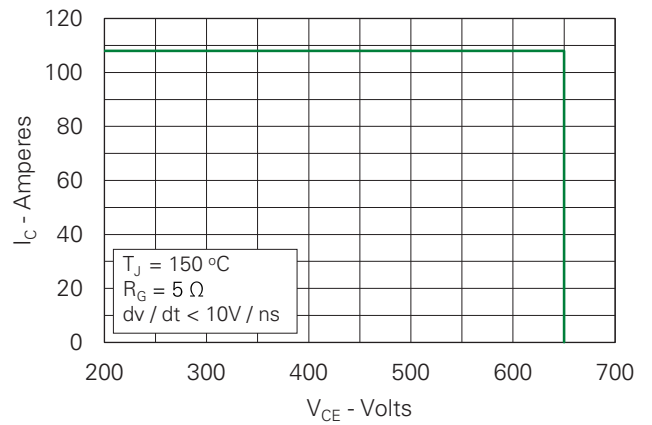


Fig. 11. Maximum Transient Thermal Impedance

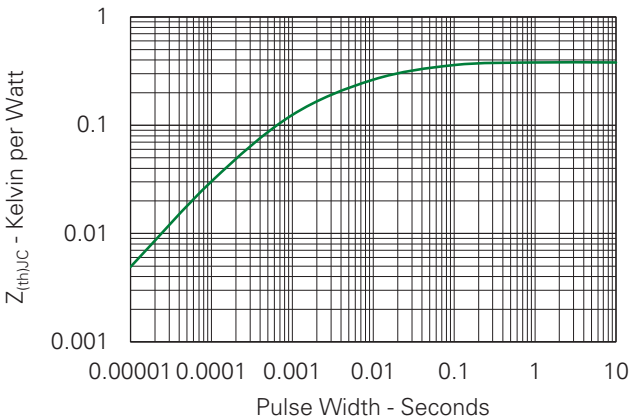
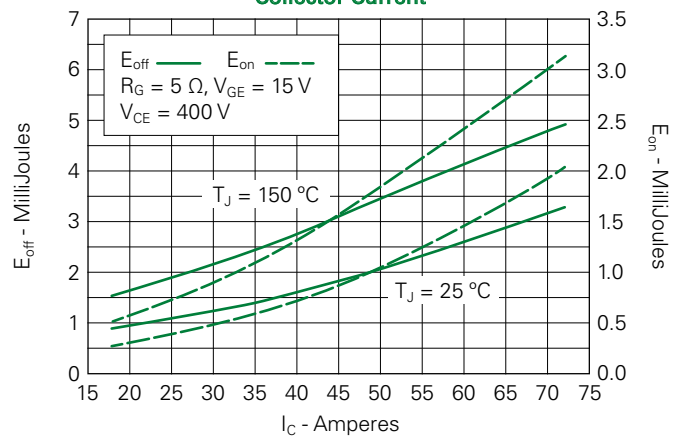
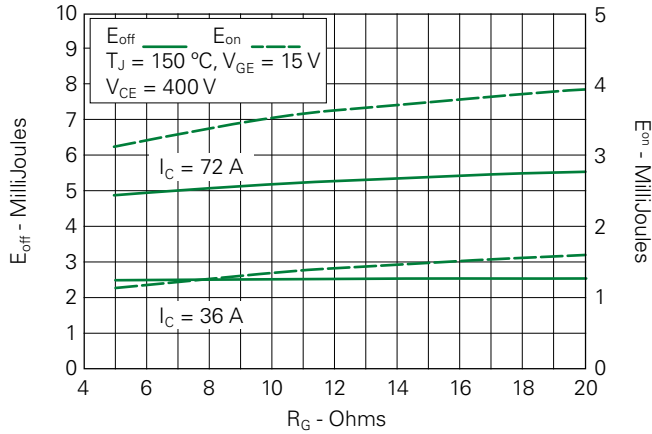


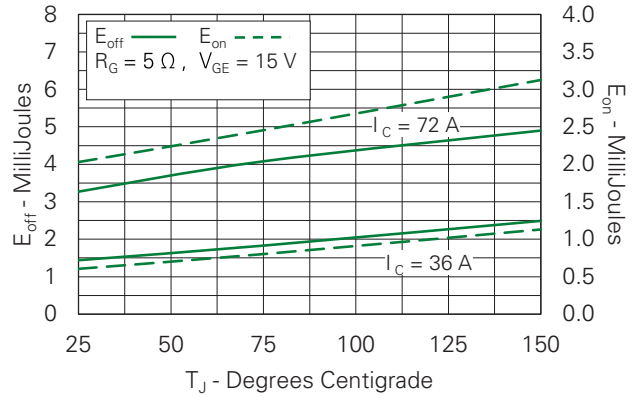
Fig. 12. Inductive Switching Energy Loss vs. Collector Current



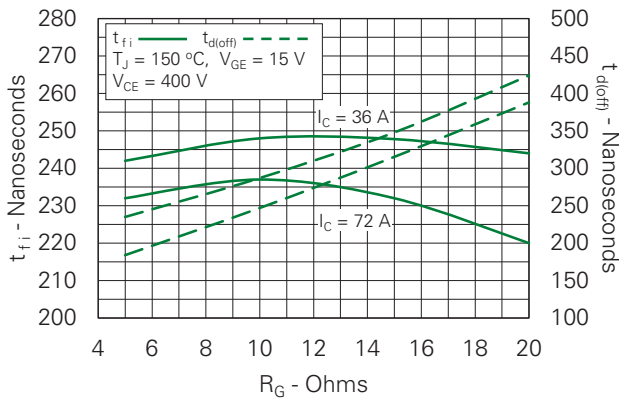
**Fig. 13. Inductive Switching Energy Loss vs. Gate Resistance**



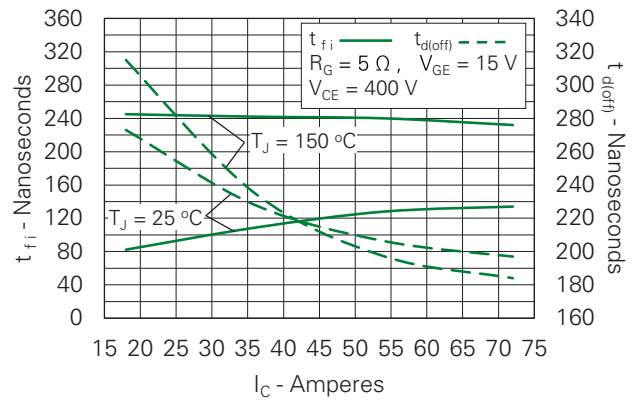
**Fig. 14. Inductive Switching Energy Loss vs. Junction Temperature**



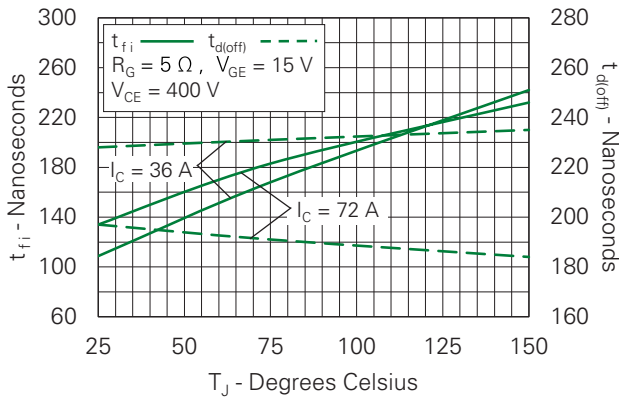
**Fig. 15. Inductive Turn-off Switching Times vs. Gate Resistance**



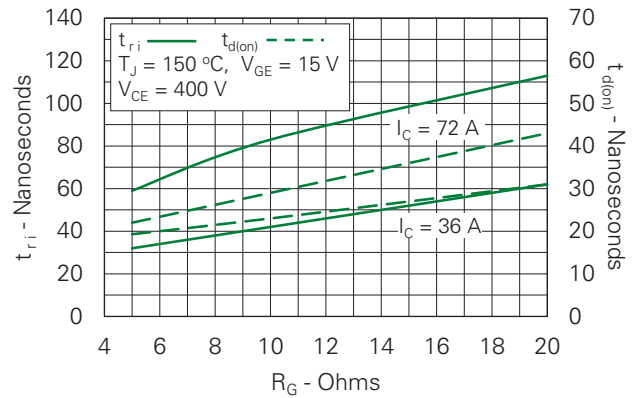
**Fig. 16. Inductive Turn-off Switching Times vs. Collector Current**



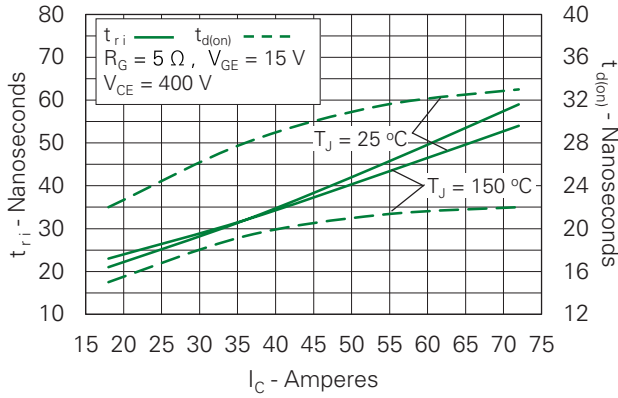
**Fig. 17. Inductive Turn-off Switching Times vs. Junction Temperature**



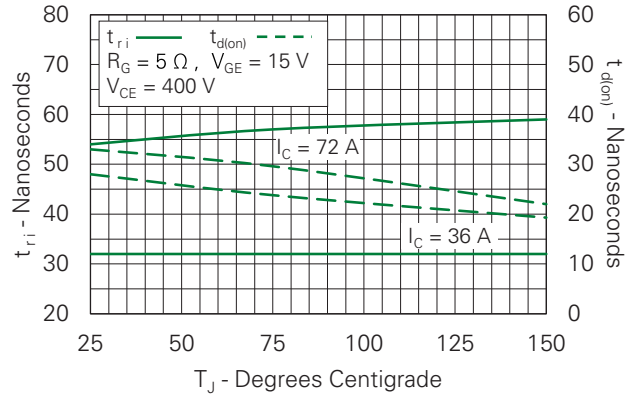
**Fig. 18. Inductive Turn-on Switching Times vs. Gate Resistance**



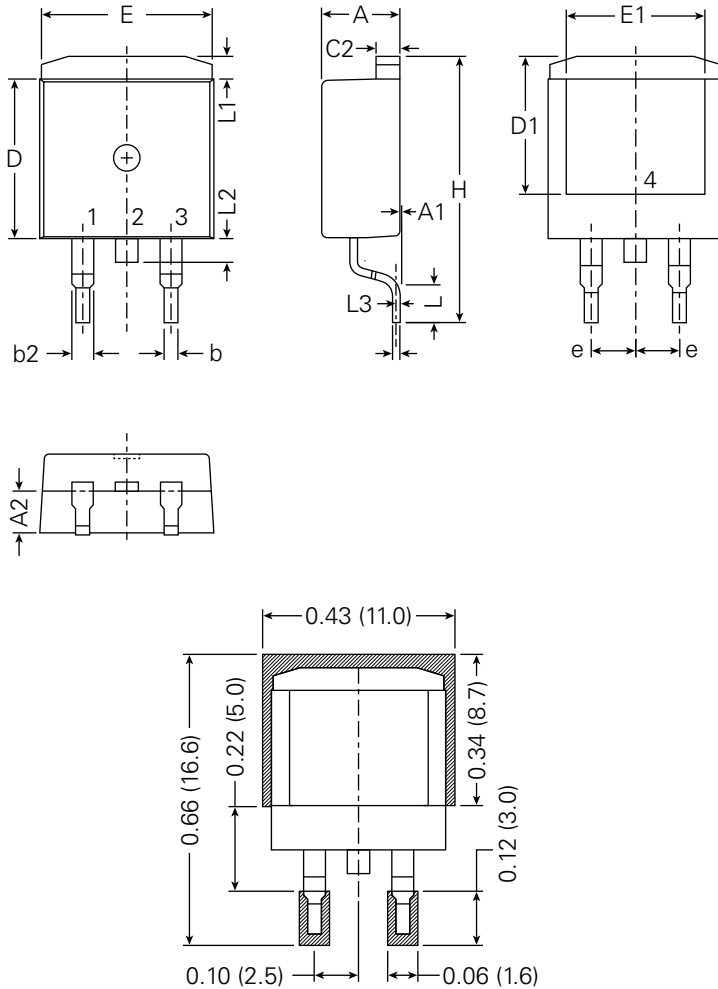
**Fig. 19. Inductive Turn-on Switching Times vs. Collector Current**



**Fig. 20. Inductive Turn-on Switching Times vs. Junction Temperature**



**Part Outline Drawings** TO-263 (IXYA)



MINIMUM PCB FOOT PRINT LAYOUT

Symbol	Inches		Millimeters	
	Min.	Max.	Min.	Max.
A	0.170	0.185	4.30	4.70
A1	0.000	0.008	0.00	0.20
A2	0.091	0.098	2.30	2.50
b	0.028	0.035	0.70	0.90
b2	0.046	0.060	1.18	1.52
c	0.018	0.024	0.45	0.60
C2	0.049	0.060	1.25	1.52
D	0.340	0.370	8.63	9.40
D1	0.300	0.327	7.62	8.30
E	0.380	0.410	9.65	10.41
E1	0.270	0.330	6.86	8.38
e	0.100 BSC		2.54 BSC	
H	0.580	0.620	14.73	15.75
L	0.075	0.105	1.91	2.67
L1	0.039	0.060	1.00	1.52
L2	-	0.070	-	1.77
L3	0.100 BSC		0.254 BSC	

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